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Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1. (amended) A semiconductor device, comprising:
a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;
an extended adhesive material layer disposed on the top side of the base carrier, the adhesive material layer covering the central area and a large portion of the peripheral area of the base carrier top surface, wherein the adhesive material extends beyond edges of the die a distance greater than about two times a thickness of the die; and
an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.
2. (original) The semiconductor device of claim 1, wherein the base carrier comprises a paddle.
3. (previously amended) The semiconductor device of claim 2, further comprising a leadframe electrically connected to the integrated circuit die.
4. (original) The semiconductor device of claim 3, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.

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5. (canceled)

6. (twice amended) A semiconductor device, comprising:
a base carrier having a top side and a bottom side, the top side having a central area for receiving an integrated circuit die and a peripheral area;

an extended adhesive material layer disposed on the top side of the base carrier, wherein the adhesive material layer is dispensed on the top side of the base carrier in an "X" shaped pattern, the "X" shaped pattern including two bisecting lines, wherein the two bisecting lines extend beyond the central area and into the peripheral area of the base carrier top surface, wherein the adhesive material extends beyond edges of the die a distance greater than about two times a thickness of the die;
and

an integrated circuit die attached to the base carrier with the adhesive material layer at the central area.

7. (original) The semiconductor device of claim 6, wherein the "X" shaped pattern of adhesive material further includes a first line extending from a middle part of the peripheral area of a first side of the base carrier to a middle part of the peripheral area of a second, opposing side of the base carrier such that the adhesive material layer forms a six pointed star.

8. (original) The semiconductor device of claim 7, wherein the "X" shaped pattern of adhesive material further includes a second line extending from a middle part of the peripheral area of a third side of the base carrier to a middle part of the peripheral area of a fourth, opposing side of the

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base carrier such that the adhesive material layer forms an eight pointed star.

9. (original) The semiconductor device of claim 6, wherein the base carrier comprises a paddle.

10. (previously amended) The semiconductor device of claim 9, further comprising a leadframe electrically connected to the integrated circuit die.

11. (original) The semiconductor device of claim 10, further comprising an encapsulant surrounding the base carrier, the integrated circuit die and at least a portion of the leadframe.

12. (cancelled)

13. (withdrawn) A method of attaching an integrated circuit die to a base carrier comprising the steps of:

dispensing an adhesive material onto a central area of a top surface of the base carrier, wherein the central area is sized to receive the integrated circuit die and the central area is surrounded by a peripheral area; and

attaching a bottom surface of the integrated circuit die to the central area on the top surface of the base carrier with the adhesive material, wherein the adhesive material dispensed onto the top surface of the base carrier extends well into the peripheral area of the base carrier top surface.

14. (withdrawn) The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the dispensed

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adhesive material covers substantially the entire top surface of the base carrier.

15. (withdrawn) The method of attaching an integrated circuit die to a base carrier of claim 13, wherein the adhesive material is dispensed onto the base carrier top surface in a predetermined pattern.

16. (withdrawn) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an "X" pattern.

17. (withdrawn) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises a six point star pattern.

18. (withdrawn) The method of attaching an integrated circuit die to a base carrier of claim 15, wherein the predetermined pattern comprises an eight point star pattern.

19. (Amended) An improved [method of attaching an] integrated circuit having a die attached to a base carrier, wherein a top side of the base carrier has a central area for receiving the die and a peripheral area surrounding the central area, the improvement comprising:

an extended adhesive material layer, disposed on the top side of the base carrier and covering the central area and a large portion of the peripheral area, for attaching the die to the base carrier, wherein the adhesive material extends beyond edges of the die a distance greater than about two times a thickness of the die.